

SEP 10 2003

OFFICIAL

Serial No. 09/879,724  
Attorney Docket No. F0522  
Firm Reference No. AMDSP0414US

Reply to Office Action Dated August 19, 2003  
Reply Dated September 9, 2003

## CERTIFICATE OF MAILING OR FACSIMILE TRANSMISSION UNDER 37 CFR 1.8(a)

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Ahmed N. Sefer

*Linda McElroy*  
Linda McElroy

September 9, 2003

Date

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of:

Applicant: Dong-Hyuk Ju et al.

Serial No: 09/879,724

Filing Date: June 12, 2001

Art Unit: 2826

Examiner: Ahmed N. Sefer

Confirmation No: 4898

Title: LEAKY, THERMALLY CONDUCTIVE INSULATOR MATERIAL (LTCIM) IN  
SEMICONDUCTOR-ON-INSULATOR (SOI) STRUCTURE

Mail Stop AF: Expedited Procedure  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Mail Stop AF  
EXPEDITED  
PROCEDURE

## REPLY TO OFFICE ACTION DATED AUGUST 19, 2003

Dear Sir:

Favorable reconsideration of the above-identified application is respectfully requested in view of the following amendments and comments. It is believed that the amendments contained herein raise no new issues, do not require an additional search and place the application in a better condition for allowance and/or appeal. Accordingly, entry of the amendment is considered proper.

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**Amendments in the Claims** are reflected in the listing of claims that begins on page 3 of this paper.

**Remarks** begin on page 8 of this paper.